

### **REMARKS**

Reconsideration of the application as presently amended is respectfully requested. Claims 1-29 have been amended. No claims have been cancelled or added. Applicant respectfully submits that no new matter has been added by the amendments made herein.

Claims 5-27 and 29 stand objected to as being improper multiple dependent claims. Applicant has removed all multiple dependencies from the claims and respectfully requests that the objection be withdrawn.

Claims 1-2 and 4 stand rejected under 35 U.S.C. 102(b) as anticipated by WO 02/084784A to Hankui et al. ("Hankui"). Hankui is directed to a wireless portable device that has a multi-layer printed circuit board ("PCB"). The PCB is typically 0.8-1.6 mm in thickness. Top and bottom external layers of the PCB are typically ground layers. Hankui discloses a current restriction structure that is used to suppress coupling between a radio circuit block and a digital circuit block. The current restriction structure is implemented in one or more layers of the multi-layer PCB disclosed by Hankui.

Applicant respectfully submits that Hankui fails to disclose at least one distinguishing feature of claim 1 as amended herein, namely, at least one conducting surface situated over a part of a ground plane and separated from the part of the ground plane by a distance of 0.8-20 mm. The current restriction structure of Hankui is an integral part of the PCB of the device disclosed therein and typically requires modification of the design of the PCB. Outer layers of a PCB are typically arranged as ground layers; therefore, in such cases, the current restriction structure of Hankui is placed in inner layers of the PCB and typically at a distance of less than 0.8 mm.

In contrast, the invention claimed in amended claim 1 requires that at least one conducting surface be separated from part of the ground claim by a distance of 0.8-20 mm. In various embodiments of the invention, this increased separation relative to Hankui may avoid the need to change or modify configuration of layers of the PCB. In contrast, in Hankui, changes in the design of PCB layers of a wireless device needed to implement the current restriction

structure could, in some cases, result in a significant redesign of placement and routing of components on the PCB included therein.

For at least the reasons set forth above, Applicant respectfully submits that amended claim 1 distinguishes over Hankui and is in condition for allowance. Withdrawal of the rejection of amended claim 1 as anticipated by Hankui is respectfully requested.

Dependent claims 2 and 4-27 depend from and further limit independent claim 1 in a patentable sense. For at least the same reasons as those set forth above, each of these claims is also deemed to distinguish over Hankui.

Independent claim 29 is deemed to be allowable for similar reasons to those set forth above with respect for independent claim 1. Applicant respectfully draws the attention of the examiner to the fact that independent claim 29 has also been rewritten so that it does not reference any other claim.

Applicant appreciates the examiner's allowance of claim 28 and indication of allowable subject matter with respect to claim 3.

Many of the claim amendments made herein were for clarity purposes and in order to better conform the claims to U.S. practice, rather than in response to any objection or rejection of the examiner.

In view of the above amendment, Applicant respectfully submits that the present application is in condition for allowance. A Notice to that effect is respectfully requested.

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Respectfully submitted,

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